

Effect of CuO addition on the microstructure and electrical properties of SnO₂-based varistor

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Abstract The effect of CuO addition on the properties of (Co, Nb, Cr)-doped SnO₂ varistors were investigated. The samples with different CuO concentrations were fabricated by the conventional ceramic method and sintered at 1,200, 1,250, 1,300 and 1,350 °C for 2 h. It is found that the nonlinear coefficient presents a peak value at 0.2 mol % CuO addition. The leakage current density decreases with increasing CuO from 0 to 0.2 mol %, and then increases when the concentration of CuO is above 0.2 mol %. The breakdown electrical field decreases from 356 to 248 V/mm with increasing CuO from 0 to 0.6 mol %. The optimal samples obtained by doping CuO with 0.2 mol % and sintered at 1,300 °C have the highest nonlinear coefficient value of 31 and the lowest leakage current density of 2 μA/cm².

1 Introduction

The rutile crystalline structural SnO₂ is an n-type semiconductor with many interesting electronic properties. In the past, it is widely used in gas sensors and wet sensors. However, since it is first studied as varistors by the group of Pianaro, a great number of papers on the new SnO₂-based varistors have been published [1–4]. Compared with the commercial ZnO varistors, it has good thermal

conductivity and high temperature resistance. The main characteristic of this new varistor system is its simple microstructure, which has only one phase with X-ray precision. The single-phase microstructure of SnO₂ based varistors maybe resolve the problem of the degradation of the commercial ZnO–Bi₂O₃ based varistors.

In the past decades, many dopants have been studied, such as ZnO, CoO, MnO, Nb₂O₅, CuO, Ta₂O₅, Cr₂O₃, Al₂O₃ [5–13]. And the effects of these dopants are different in SnO₂-based varistor. ZnO, CoO, MnO have significant role to improve the density, Nb₂O₅ and Ta₂O₅ mainly improve the conductivity, and Cr₂O₃ and Al₂O₃ mainly improve current–voltage characteristic of SnO₂-based ceramics. From the recent publications, CoO, Nb₂O₃ and Cr₂O₃ doped SnO₂-based varistors show the excellent nonlinearity and high density [4, 14–17].

In the previous works [18, 19], the effects of CuO on the grain size, density, nonlinearity, and dielectric property of the SnO₂–Ni₂O₃–Nb₂O₅ and SnO₂–Co₂O₃–Ta₂O₅ varistors were investigated. In this work, the effects of CuO addition and sintering temperature on the microstructure and electrical properties of the Co₂O₃–Nb₂O₃–Cr₂O₃ doped SnO₂ varistors were investigated in detail. It is found that CuO addition and sintering temperature could evidently adjust the microstructure, and as a result, the breakdown electrical field decreases, the nonlinearity improves and the leakage current decreases.

2 Experimental

Five raw materials of analytic level, SnO₂ (99.8 %), Co₂O₃ (99 %), Nb₂O₅ (99.5 %), CuO (99 %) and Cr₂O₃ (99 %), were used to prepare the SnO₂ based varistors. The varistors were fabricated by a conventional electrical ceramics

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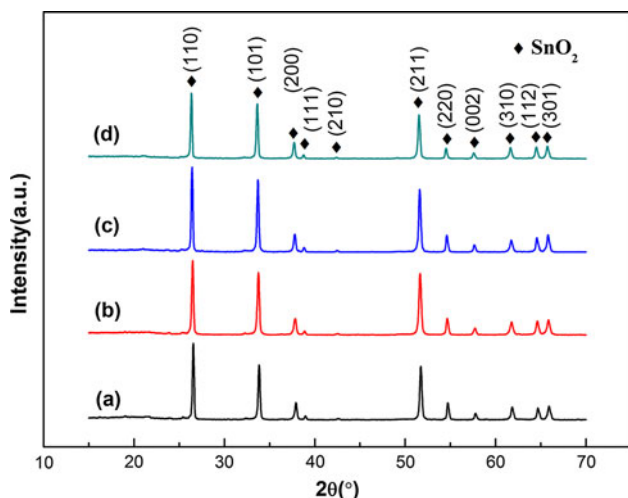


Fig. 1 XRD patterns of the SnO₂ based varistors doped with different amount of CuO at 1,300 °C: (a) without CuO; (b) 0.1 mol %; (c) 0.2 mol %; (d) 0.6 mol %

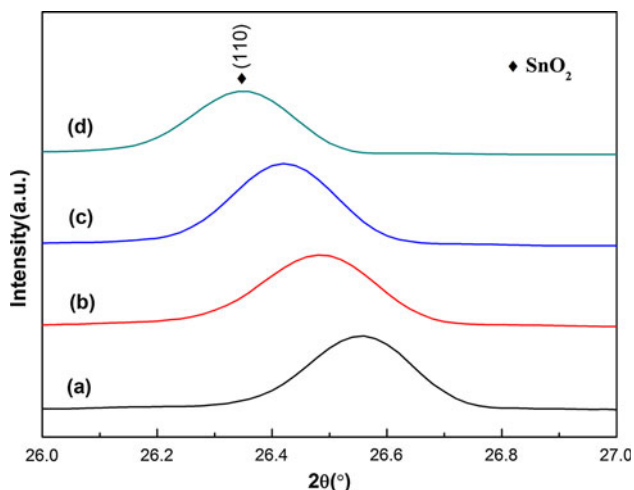


Fig. 2 The shifting of SnO₂ diffraction peaks with different amount of CuO at 1,300 °C

processing method. The compositions in molar ratios were (98.2 – X) % SnO₂ + 0.75 % Co₂O₃ + 0.05 % Nb₂O₅ + 0.05 % Cr₂O₃ + X % CuO, with X = 0.0, 0.1, 0.2, 0.4 and 0.6 mol %. The mixtures of raw materials were milled in nylon kettle for 4 h at 800 r/min with ZrO₂ balls and distilled water, the ratio of balls to the mixed powders and water was 2:1:1. Then as milled slurry was dried, mixed with 0.8 wt % of PVA binder and pressed into pellets (10.00 mm × 1.32 mm) by uniaxial pressing (2.5 MPa). After burning out the PVA binder at 650 °C for 2 h, the pellets were respectively sintered at 1,200, 1,250, 1,300, and 1,350 °C for 2 h, and then cooled to the room temperature at a rate of 5 °C/min.

The microstructures of the surfaces were analyzed by scanning electron microscopy (SEM, Model JSM-5610LV,

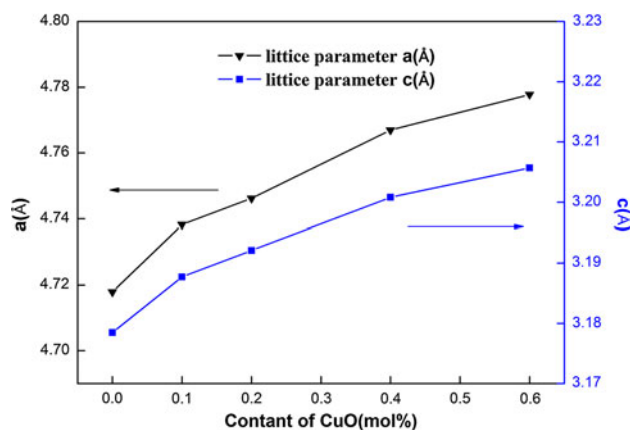
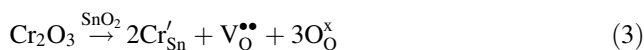
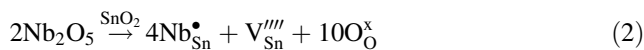
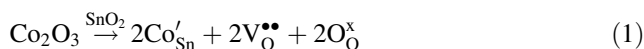


Fig. 3 Lattice parameter of the SnO₂ as a function of CuO content at 1,300 °C

JEOL), and the phase composition was determined by X-ray powder diffraction (XRD). The grain sizes (d) were calculated by microstructure linear analysis [20]. The sintered density (ρ) of ceramics was measured by the Archimedes method in distilled water. For the electrical measurements, silver electrodes (0.5 cm²) were made on both surfaces of the sintered pellets, after which the pellets were heat-treated at 600 °C for 2 h. The I–V characteristics were measured by using a DC parameter instrument for varistors (Model CJ1001). The voltage gradient (V_{1mA}) was determined at a current of 1 mA and nonlinear coefficient (α) was obtained from the equation of $\alpha = 1/\lg(V_{1mA}/V_{0.1mA})$. The leakage current (I_L) was measured at 0.75 V_{1mA} .

3 Results and discussion

Figure 1 illustrates the XRD patterns of the as-prepared SnO₂-based varistor ceramics with different amounts of CuO doping sintered at 1,300 °C for 2 h. There is no any second phase detected in all samples except the SnO₂ rutile phase, which is consistent with the former work [10]. The same trend is observed for samples sintered at 1,200, 1,250, and 1,350 °C. All dopants introduced to the SnO₂ matrix form a stable solid solution according to Eqs. (1), (2), (3) and (4).



The XRD patterns between the $2\theta = 26\text{--}27^\circ$ of the sintered products contained different amount of CuO are shown in Fig. 2. It is important to note that the peaks of the SnO₂ diffraction peaks shift towards lower angles with

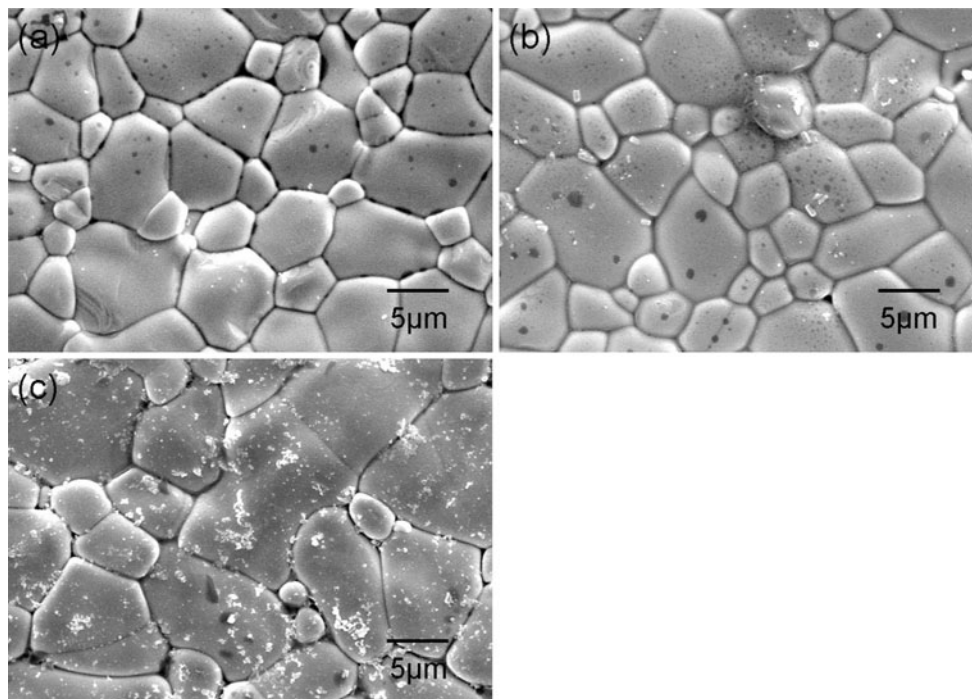


Fig. 4 SEM analysis of SnO₂ varistor ceramics doped with various amount of CuO sintered at 1,300 °C: **a** without CuO; **b** 0.2 mol % CuO; **c** 0.6 mol % CuO

Table 1 Characteristics of the samples doped with different contents of CuO

CuO (mol %)	α	E_B (V/mm)	I_L ($\mu\text{A}/\text{cm}^2$) ^a	Grain size (μm)	Relative density (%) ^b	Shrinkage rate (%)
0.0	25	356	11	4.6	94.9	14.9
0.1	28	343	8	4.7	95.1	15.0
0.2	31	320	2	5.0	95.3	15.1
0.4	29	274	7	5.8	95.2	15.1
0.6	26	248	10	6.2	95.1	15.0

^a I_L is measured at 0.75 V_{1mA}

^b Theoretical density of SnO₂ is 6.95 g/cm³

increasing of CuO content, indicating that the lattice parameter of the as-sintered SnO₂ increases with increasing of CuO content. This is attributable to the solid solution formation between SnO₂ and CuO. The ionic crystal radii of Sn⁴⁺ and Cu²⁺ are 0.69 and 0.73 Å, respectively. Consequently, one can conclude that the Sn site of SnO₂ lattice could be easily substituted by Cu to form substitutional limited solid solutions. The lattice parameters of the as-sintered Sn_{1-x}Cu_xO samples as a function of CuO content are shown in Fig. 3. It could be observed that both a- and c-axis of the SnO₂ increase as the amount of CuO increases from 0 to 0.6 mol %. Especially, the a-axis decreases more evidently from 4.7179 to 4.7778 Å by 1.26 %, which is obeyed the generally known Vegard's law.

The effect of CuO concentration on the microstructure of the samples is shown in Fig. 4. It reveals that the surfaces of all as fabricated products possess a plain texture with the expected clear grain boundary for ceramic materials.

The grain clearance of the samples with 0.2 mol % CuO added is much smaller than those in the samples without CuO and with 0.6 mol % CuO addition. The grain distribution of the samples with 0.2 mol % CuO is also the most homogeneous. The SnO₂ grain size gently increases from 4.6 to 5.0 with the increasing amount of the CuO content from 0 to 0.2 mol %. But it increases evidently from 5.0 to 6.2 with increasing amount of CuO content from 0.2 to 0.6 mol %. It is indicated that few amount of CuO addition mainly improves the density (shown in Table 1) and uniform dispersion of the microstructure of the resultant samples. However, an excess of CuO addition promotes grain growth obviously. That is because CuO will melt at high temperature. It is the liquid CuO at the grain boundary that proved the uniform distribution of dopant and density of the SnO₂ samples. The SnO₂ grain size increases with the overmuch addition of CuO because the substitution of Cu²⁺ for Sn⁴⁺ increases the activity of SnO₂ by means of distortion of the

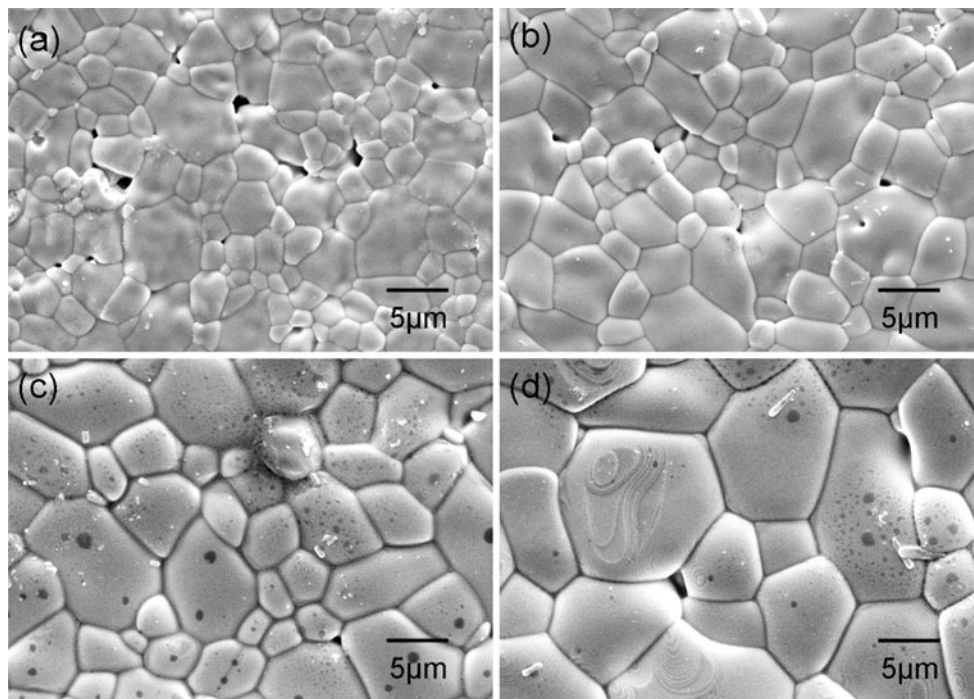


Fig. 5 SEM analysis of SnO₂ varistor ceramics at different temperatures doped with 0.2 mol % of CuO: **a** 1,200 °C; **b** 1,250 °C; **c** 1,300 °C; **d** 1,350 °C

Table 2 Characteristics of the samples doped with 0.2 mol % CuO sintered at different temperatures

Sintering temperature (°C)	α	E_B (V/mm)	I_L ($\mu\text{A}/\text{cm}^2$) ^a	Grain size (μm)	Relative density (%) ^b	Shrinkage rate (%)
1,200	24	664	22	2.8	94.2	14.4
1,250	27	430	16	4.3	94.8	14.8
1,300	31	320	2	5.0	95.3	15.1
1,350	28	253	7	8.4	95.2	15.1

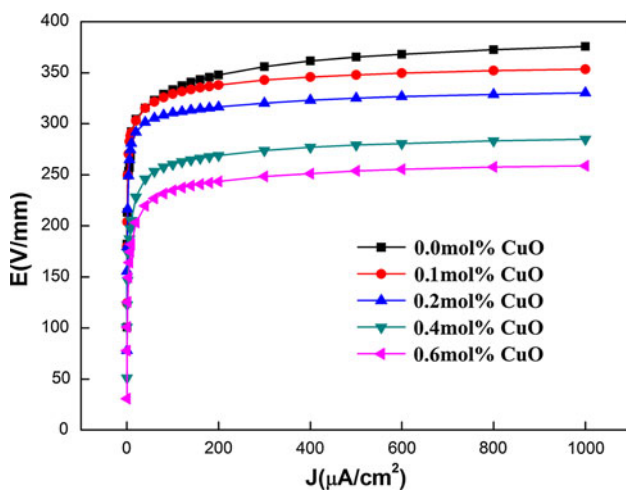


Fig. 6 *I*–*V* character of the samples doped with different contents of CuO sintered at 1,300 °C

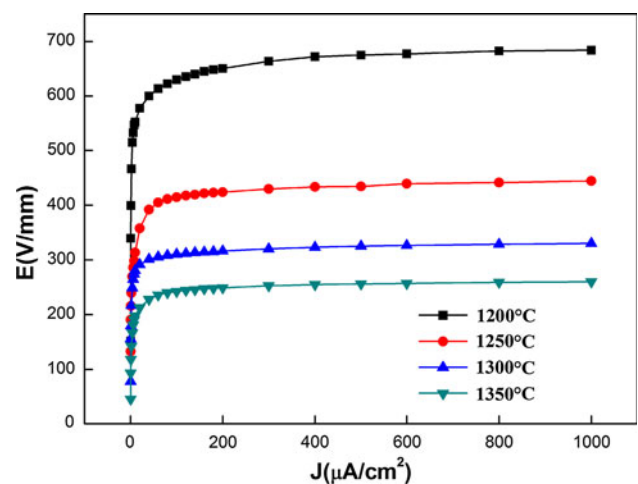


Fig. 7 *I*–*V* character of the 0.2 mol % CuO added samples sintered at different temperatures

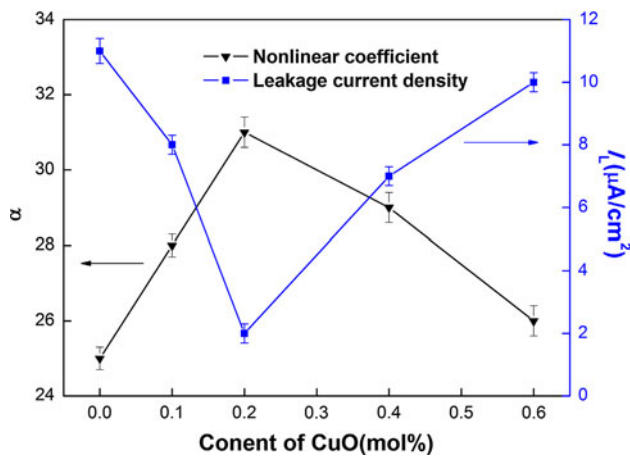


Fig. 8 Nonlinear coefficient and leakage current density of the samples doped with different contents of CuO sintered at 1,300 °C

SnO₂ lattice, as discussed in the XRD test. In addition, as seen in the Fig. 5, when the sintering temperature increases to 1,300 °C, the structure is very dense and the grain boundary is very clear, which implies that the SnO₂ grains are well crystallized with good integrality. The grain size grows from 2.8 to 5.0 with an average value. The sintered density of the samples increased from 6.55 to 6.62 g/cm³ corresponding to 94.2–95.3 % of the theoretical density (TD) (pure SnO₂, TD = 6.95 g/cm³) when the sintering temperature increases from 1,200 to 1,300 °C. However, the sintered density has little decrease when the sintering temperature up to 1,350 °C, it attributed to the volatility of the liquid at high temperatures. The details are shown in Table 2.

The electrical characteristics of the as fabricated SnO₂-based varistors as a function of CuO concentration sintered at 1,300 °C are plotted in Fig. 6. All the samples have excellent I–V curves in the figures. The breakdown electrical field decreases from 356 to 248 V/mm with increasing CuO concentration from 0 to 0.6 mol %, which can be explained according to the Eq. (5):

$$E_B = nV_{gb} \quad (5)$$

where n is the average grain number per unit length, V_{gb} , about 2.2–3 V [21], is the breakdown voltage of a grain boundary. As shown in Fig. 4, the average grain size of the sintered samples increases with the increase of the CuO concentration, as a result, the breakdown electrical field, E_B , decreases. And the breakdown electrical field decreases from 664 to 253 V/mm with increasing sintering temperature from 1,200 to 1,350 °C, as shown in Fig. 7.

Figure 8 shows that the nonlinear coefficient and leakage current density of the samples with different CuO concentration sintered at 1,300 °C. The nonlinear coefficient has a peak value of 31 when added 0.2 mol % CuO. As the CuO concentration increases above 0.2 mol %, the nonlinear coefficient decreases. According to the previous

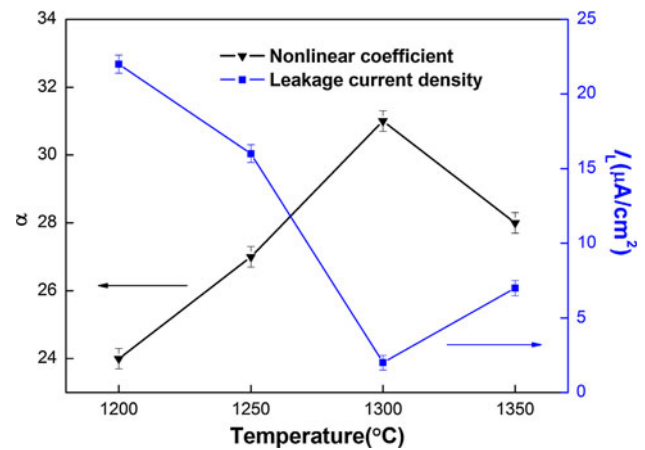


Fig. 9 Nonlinear coefficient and leakage current of the 0.2 mol % CuO added samples sintered at different temperatures

work [22], the decreasing nonlinear coefficient might be associated to the reduction of the effective grain boundary. On the contrary, The leakage current density decreases firstly with the CuO concentration increasing from 0 to 0.2 mol %, and then increases gradually with the CuO concentration further increasing from 0.2 to 0.6 mol %. As shown in Fig. 4, the high density and uniform microstructure result in lowering the leakage current density of the 0.2 mol % CuO doped SnO₂ samples.

Figure 9 shows the nonlinear coefficient and leakage current density of the 0.2 mol % CuO added samples sintered at different temperatures. The nonlinear of the obtained samples is better than that at any other sintering temperature. Meanwhile, the sample sintered at 1,300 °C presents a lowest leakage current density value of 2 μA/cm². As shown in Fig. 5, when the samples with 0.2 mol % CuO addition are sintered at, the product possesses the highest dense and most homogeneous microstructure, which lead to a low leakage current density. Based above results, it can be sure that the 0.2 mol % CuO is the optimum concentration, and 1,300 °C is a appropriate temperature for synthesis of the SnO₂ based varistors.

4 Conclusions

The effect of CuO addition on the microstructure and electrical properties of SnO₂ varistors were studied in detail at different sintering temperatures. The breakdown electrical field of the SnO₂ varistors decreases with increasing CuO content. While the nonlinear coefficient possesses a peak value of 31 and the leakage current density has the minimum value of 2 μA/cm² at 0.2 mol % CuO sintered at 1,300 °C. Hence, the 0.2 mol % is the optimum CuO content for SnO₂ varistors, and 1,300 °C is the best sintering temperature for this system.

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